

HEAT DISSIPATION PACKAGE AND METHOD OF MANUFACTURING THE SAME

ABSTRACT

A method of manufacturing heat dissipation packages includes the steps as following. Heat dissipation layers each including a main portion and a carry portion are provided, the main portion has an outer surface and an inner surface, and the carry portion protrudes from the inner surface. An uncured thermally conductive material is provided on a carry surface of the carry portion and it can flow within the carry surface only. Electronic components are bonded to the uncured thermally conductive material to be connected to the heat dissipation layers. Owing to the uncured thermally conductive material is restricted to flow within the carry surface, it is able to prevent the electronic components from shifting caused by cohesion of the uncured thermally conductive material.

Fig. 9